

MOS FIELD EFFECT TRANSISTOR 2SK3483

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3483 is N-channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

• Low on-state resistance

 $R_{DS(on)1}$ = 52 $m\Omega$ MAX. (VGs = 10 V, ID = 14 A)

 $R_{DS(on)2} = 59 \text{ m}\Omega \text{ MAX.} (V_{GS} = 4.5 \text{ V}, I_D = 14 \text{ A})$

- Low Ciss: Ciss = 2300 pF TYP.
- · Built-in gate protection diode
- TO-251/TO-252 package

★ ORDERING INFORMATION

PART NUMBER	PACKAGE			
2SK3483	TO-251 (MP-3)			
2SK3483-Z	TO-252 (MP-3Z)			

(TO-251)

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	` '			
Drain to Source Voltage (Vgs = 0V)	VDSS	100	V	
Gate to Source Voltage (Vps = 0V)	Vgss	±20	V	
Drain Current (DC)	ID(DC)	±28	Α	
Drain Current (Pulse) Note1	D(pulse)	±60	Α	
Total Power Dissipation (Tc = 25°C)	PT	40	W	
Total Power Dissipation (T _A = 25°C)	PT	1.0	W	
Channel Temperature	Tch	150	°C	
Storage Temperature	Tstg	-55 to +150	°C	
Single Avalanche Current Note2	las	25	Α	
Single Avalanche Energy Note2	Eas	62.5	mJ	



10-252)



Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25° C, R_G = 25Ω , V_{GS} = $20 \rightarrow 0 \text{ V}$

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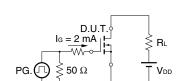
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 100 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5	2.0	2.5	V
Forward Transfer Admittance Note	y fs	V _{DS} = 10 V, I _D = 14 A	9.0	18		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 14 A		41	52	mΩ
	R _{DS(on)2}	V _{GS} = 4.5 V, I _D = 14 A		45	59	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		2300		pF
Output Capacitance	Coss	V _{GS} = 0 V		230		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		120		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50 V, I _D = 14 A		12		ns
Rise Time	tr	V _{GS} = 10 V		9		ns
Turn-off Delay Time	td(off)	R _G = 0 Ω		53		ns
Fall Time	t f			5		ns
Total Gate Charge	QG	V _{DD} = 80 V		49		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		7		nC
Gate to Drain Charge	Q _{GD}	I _D = 28 A		13		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 28 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	trr	I _F = 28 A, V _{GS} = 0 V		73		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		175		nC

Note Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

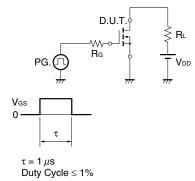
$V_{GS} = 20 \rightarrow 0 \text{ V}$ V_{DD} V_{DD} D.U.T. V_{DD} V_{DD} V_{DD} V_{DD} V_{DD} V_{DD} V_{DD}

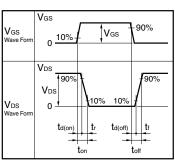


TEST CIRCUIT 3 GATE CHARGE

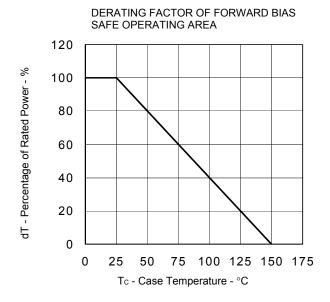
Starting Tch

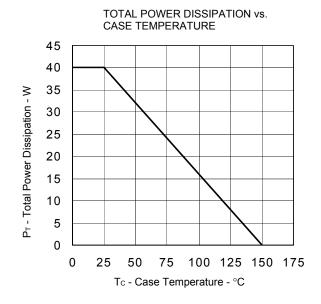
TEST CIRCUIT 2 SWITCHING TIME

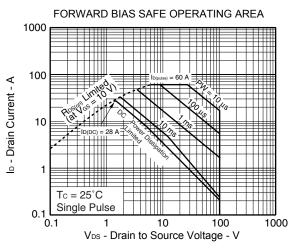


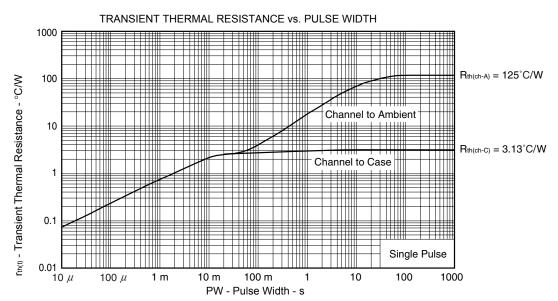


TYPICAL CHARACTERISTICS (TA = 25°C)



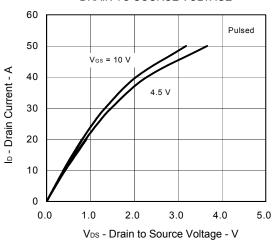




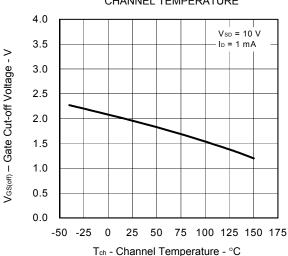


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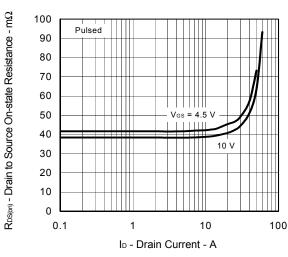
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



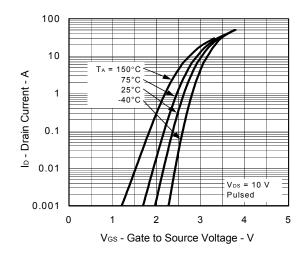
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



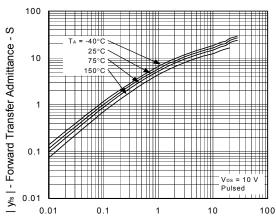
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



FORWARD TRANSFER CHARACTERISTICS

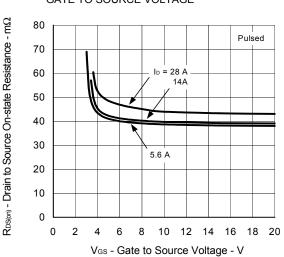


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

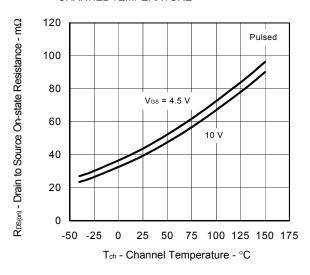


ID - Drain Current - A

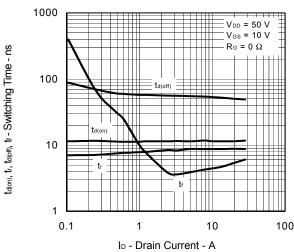
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



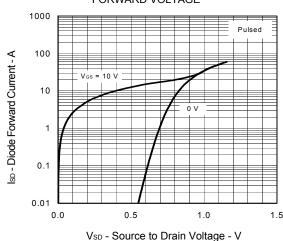
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



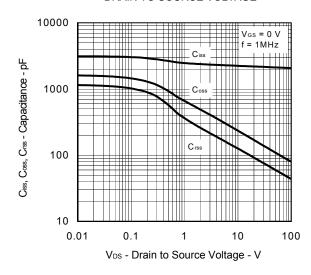
SWITCHING CHARACTERISTICS



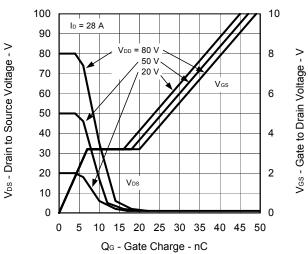
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



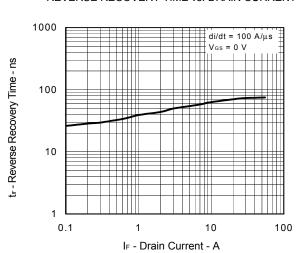
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



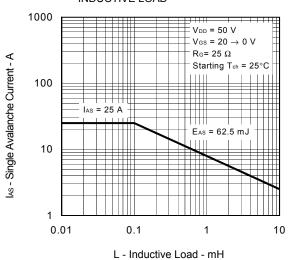
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



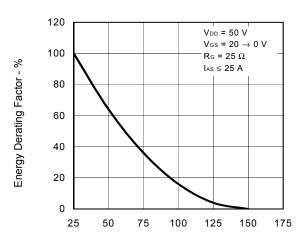
REVERSE RECOVERY TIME vs. DRAIN CURRENT



SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



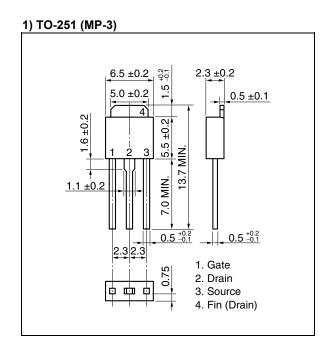
SINGLE AVALANCHE ENERGY DERATING FACTOR

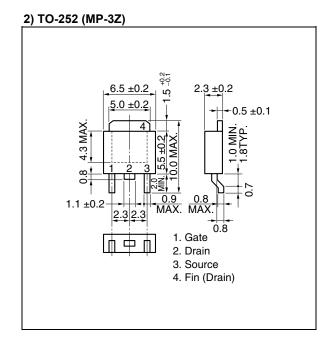


Starting Tch - Starting Channel Temperature - °C

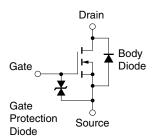


★ PACKAGE DRAWINGS (Unit: mm)





EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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